

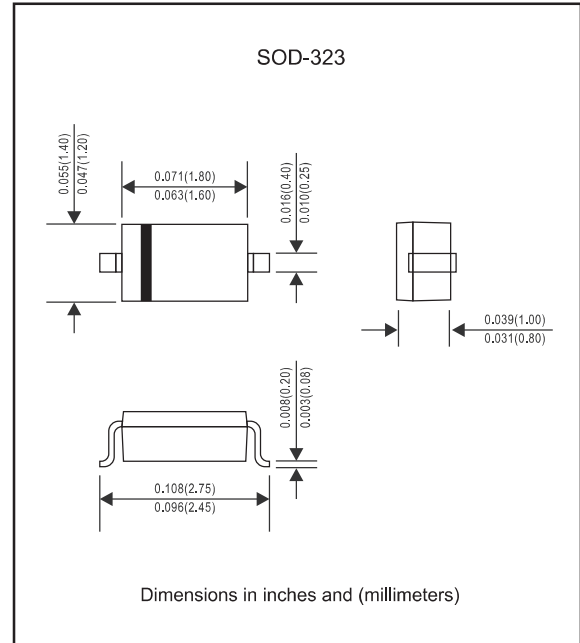
### Features

- Fast switching speed.
- Electrically identical to standard JEDEC.
- Surface mount package ideally suited for automatic insertion.
- Tiny plastic SMD package.
- RoHS Compliant
- Compliant to Halogen-free
- High Conductance.
- Silicon epitaxial planar chip.
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

### Package Outline



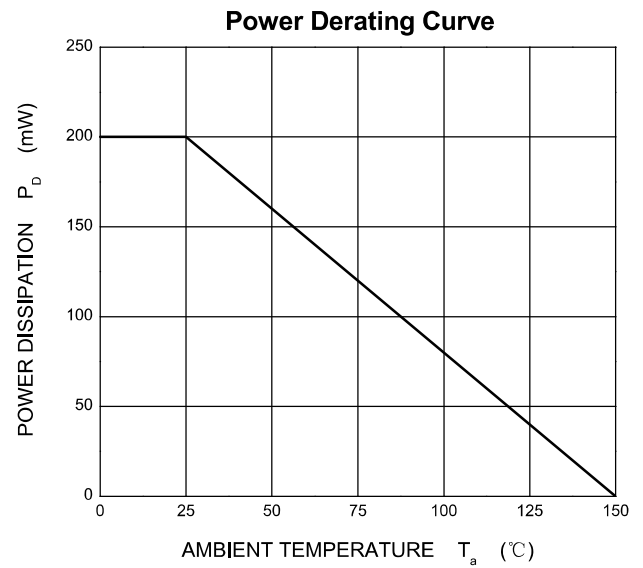
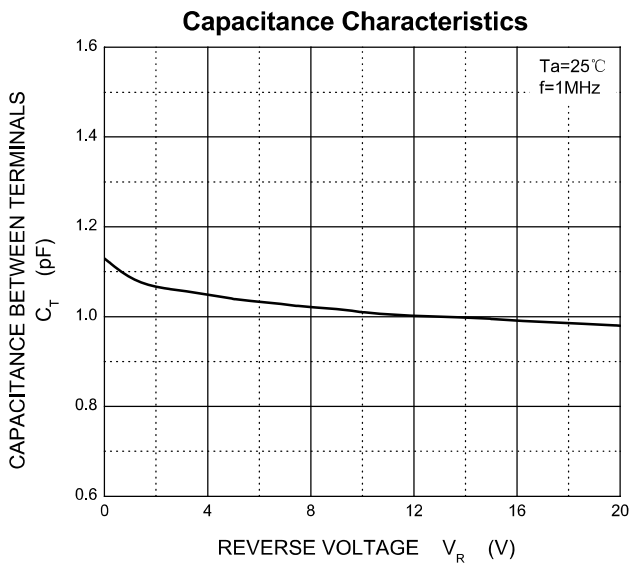
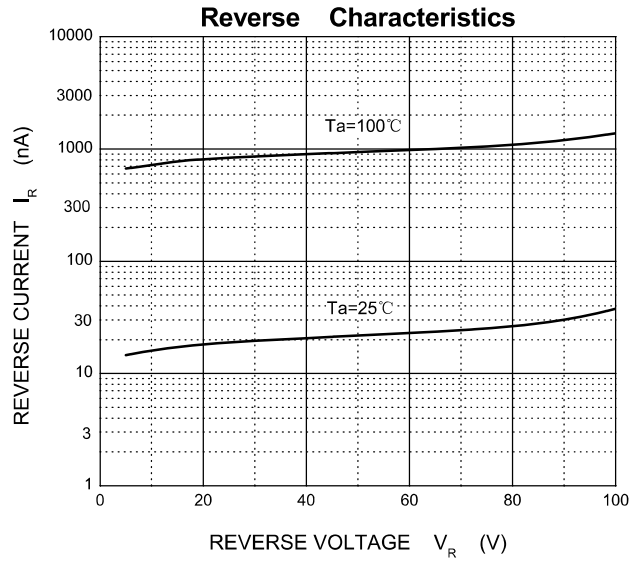
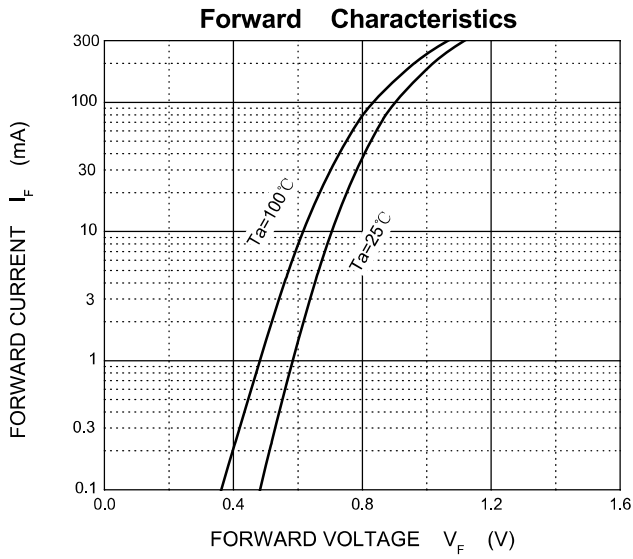
### MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted )

Symbol	Parameter	Value	Unit
$V_{RRM}$	Maximum Repetitive Reverse Voltage	100	V
$I_o$	Forward Current	0.2	A
$I_{FSM}$	Non-repetitive Peak Forward Surge Current @t= 8.3ms	2	
$P_D$	Power Dissipation	200	mW
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	500	$^\circ\text{C/W}$
$T_J, T_{stg}$	Operation Junction and Storage Temperature Range	-55~+150	$^\circ\text{C}$



### ELECTRICAL CHARACTERISTICS( $T_a=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse voltage	$V_{(BR)}$	$I_R=100\mu\text{A}$	100			V
Reverse current	$I_R$	$V_R=20\text{V}$			25	nA
		$V_R=75\text{V}$			5	$\mu\text{A}$
Forward voltage	$V_F$	$I_F=10\text{mA}$			1	V
Total capacitance	$C_{tot}$	$V_R=0\text{V}, f=1\text{MHz}$			4	pF
Reverse recovery time	$t_{rr}$	$I_F=I_R=10\text{mA}, I_{rr}=0.1\times I_R, R_L=100\Omega$			4	ns

**Typical Characteristics**



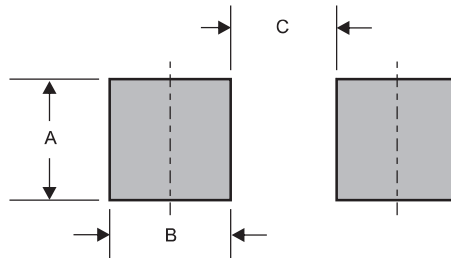
**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

**Marking**

Type number	Marking code
MMDL914	5D

**Suggested solder pad layout**



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323	0.032 (0.82)	0.022 (0.56)	0.069 (1.75)